

TPS650330-Q1 汽车摄像头 PMIC

1 特性

- 符合汽车应用要求
- 符合 AEC-Q100 1 级标准
 - 40°C 至 125°C 环境温度范围
- 三个降压转换器：
 - BUCK1 V_{IN} 范围为 4.0V 至 18.3V
 - BUCK1 V_{OUT} 范围为 2.5V 至 4.0V
 - BUCK1 输出电流高达 1500mA
 - BUCK2 和 BUCK3 V_{IN} 范围为 2.5 V 至 5.5V
 - BUCK2 和 BUCK3 V_{OUT} 范围为 0.9V 至 1.9V
 - BUCK2 and BUCK3 输出电流高达 1200mA
 - 用于降低 EMI 的扩频时钟 (SSC) 发生器
 - 2.3MHz 强制固定开关频率 PWM 模式工作
- 一个低压降 (LDO) 稳压器：
 - V_{IN} 范围为 2.5 V 至 5.5V
 - V_{OUT} 范围为 1.8V 至 3.3V
 - 低噪声和高 PSRR
 - 可通过 I²C 调节的输出电压
 - 高达 300mA 的输出电流
- 具有可湿性侧面的 4.0mm × 4.0mm 24 引脚 VQFN 封装

2 应用

- 汽车摄像头模块
 - 环视摄像头模块
 - 后视摄像头模块
 - 驾驶员监控摄像头模块
 - 同轴电缆供电 (POC) 摄像头模块
 - 电子视镜摄像头模块
 - 前视摄像头模块

3 说明

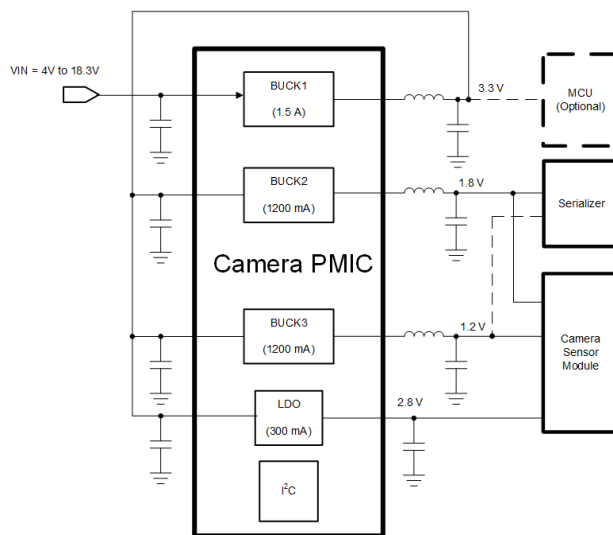
TPS650330-Q1 器件是一种高度集成的电源管理 IC，可适用于汽车摄像头模块。此器件包含三个降压转换器和一个低压降 (LDO) 稳压器。BUCK1 降压转换器的输入电压范围高达 18.3V，用于连接到同轴电缆 (PoC)。所有转换器都在强制固定频率 PWM 模式下工作。LDO 可提供 300mA 电流，并可在 2.5 V 至 5.5V 的输入电压范围内正常运行。降压转换器和 LDO 具有独立的电压输入，可实现最大的设计和排序灵活性。

TPS650330-Q1 采用 24 引脚 VQFN 封装 (4.00mm × 4.00mm)。

器件信息

器件型号 ⁽¹⁾	封装	封装尺寸 (标称值)
TPS650330-Q1	VQFN (24)	4.00mm × 4.00mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。



TPS650330-Q1 应用电路



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4 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision * (April 2019) to Revision A (December 2021)	Page
• 更新了整个文档中的表格、图和交叉参考的编号格式.....	1

5 Device and Documentation Support

5.1 Device Support

5.1.1 第三方产品免责声明

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5.2 接收文档更新通知

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5.3 支持资源

TI E2E™ [支持论坛](#) 是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的 [《使用条款》](#)。

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5.5 Trademarks

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5.6 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

5.7 术语表

[TI 术语表](#) 本术语表列出并解释了术语、首字母缩略词和定义。

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
PTPS65033000RGERQ1	ACTIVE	VQFN	RGE	24	3000	TBD	Call TI	Call TI	-40 to 125		Samples
TPS65033000RGERQ1	ACTIVE	VQFN	RGE	24	3000	RoHS & Green	SN	Level-3-260C-168 HR	-40 to 125	TPS6503 3000-Q1	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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RGE 24

GENERIC PACKAGE VIEW

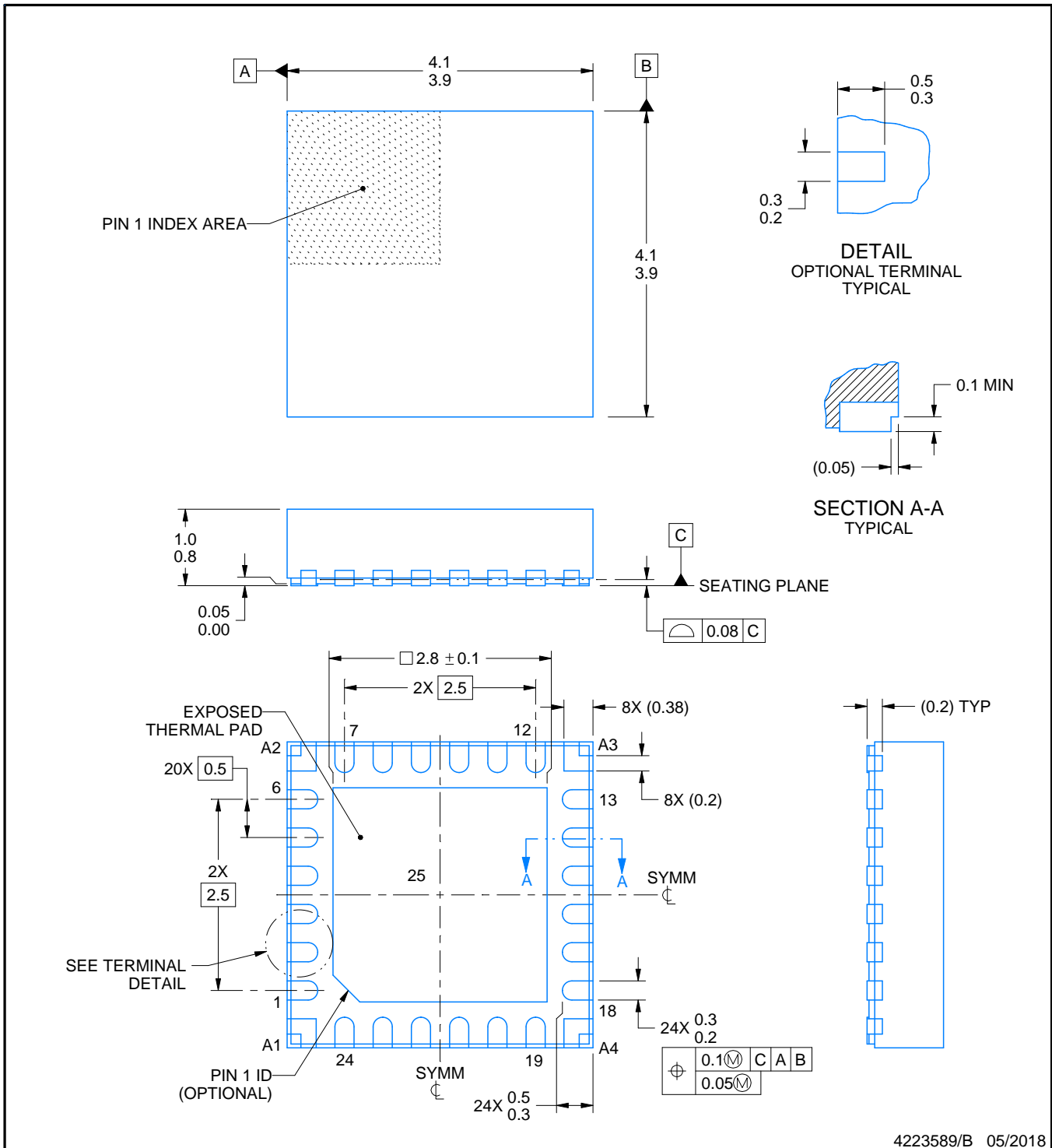
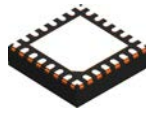
VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

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NOTES:

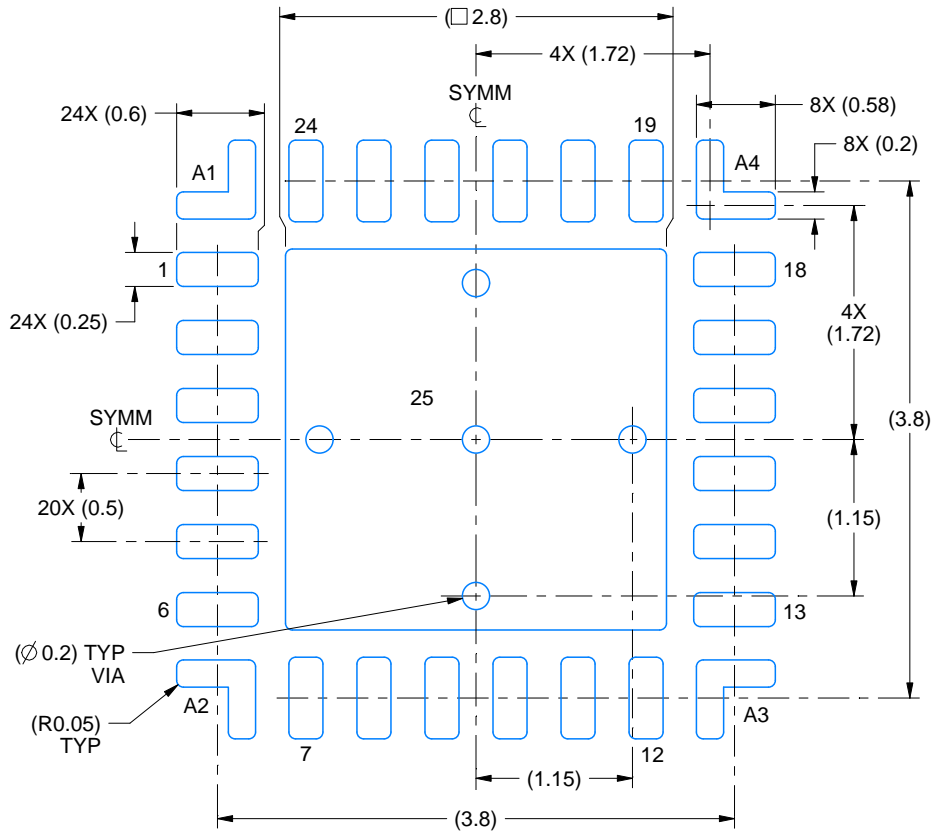
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

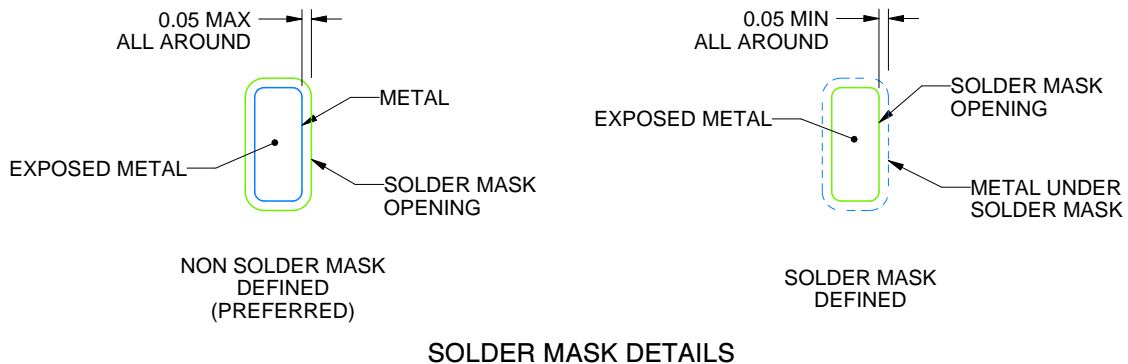
RGE0024K

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:18X



SOLDER MASK DETAILS

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NOTES: (continued)

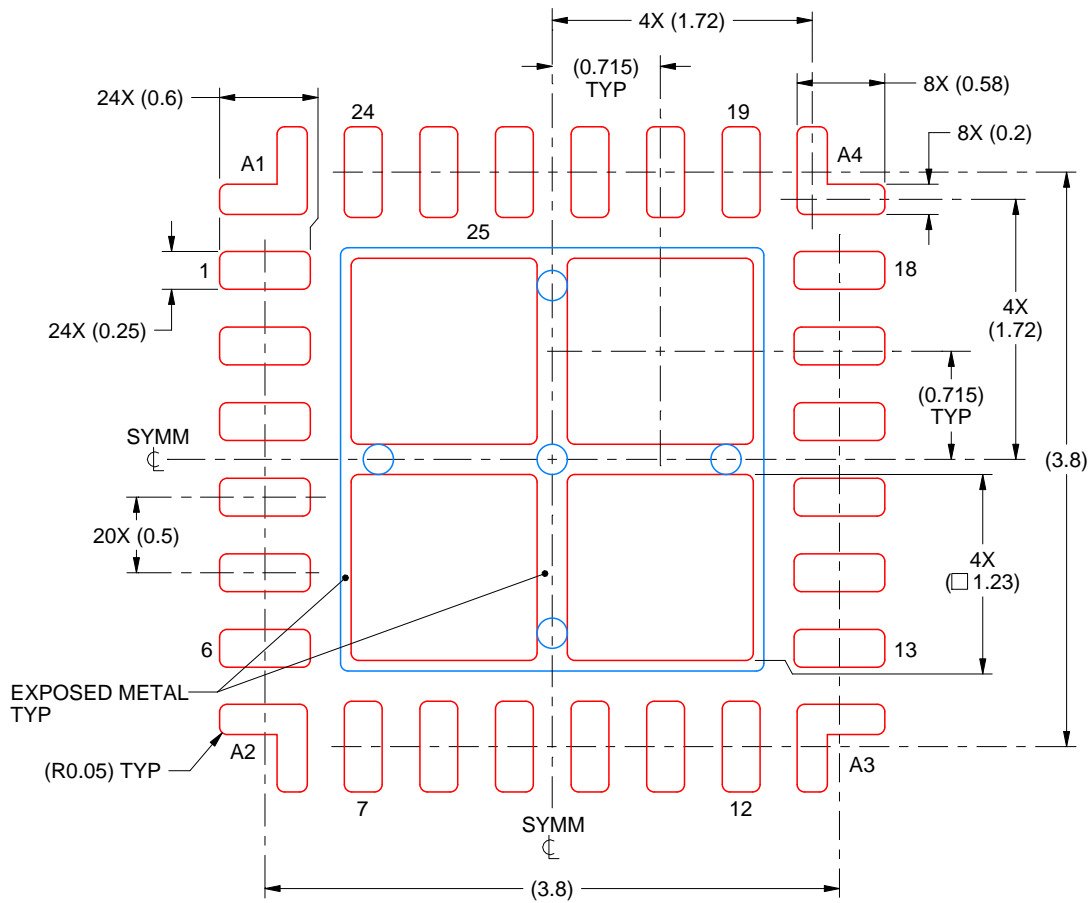
- This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
- Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

RGE0024K

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
 BASED ON 0.1 mm THICK STENCIL

THERMAL PAD 25:
 77% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
 SCALE:20X

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NOTES: (continued)

- 6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

重要声明和免责声明

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